

5/19/1

03350042 **Image available**

SEALING OF SEMICONDUCTOR DEVICE AND SEMICONDUCTOR CHIP

Pub. No.: 03 -012942 [JP 3012942 A]

Published: January 21, 1991 (19910121)

Inventor: TOTSUTA YOSHIHISA

Applicant: SHARP CORP [000504] (A Japanese Company or Corporation), JP (Japan)

Application No.: 01-148800 [JP 89148800]

Filed: June 12, 1989 (19890612)

International Class: [5] H01L-021/60

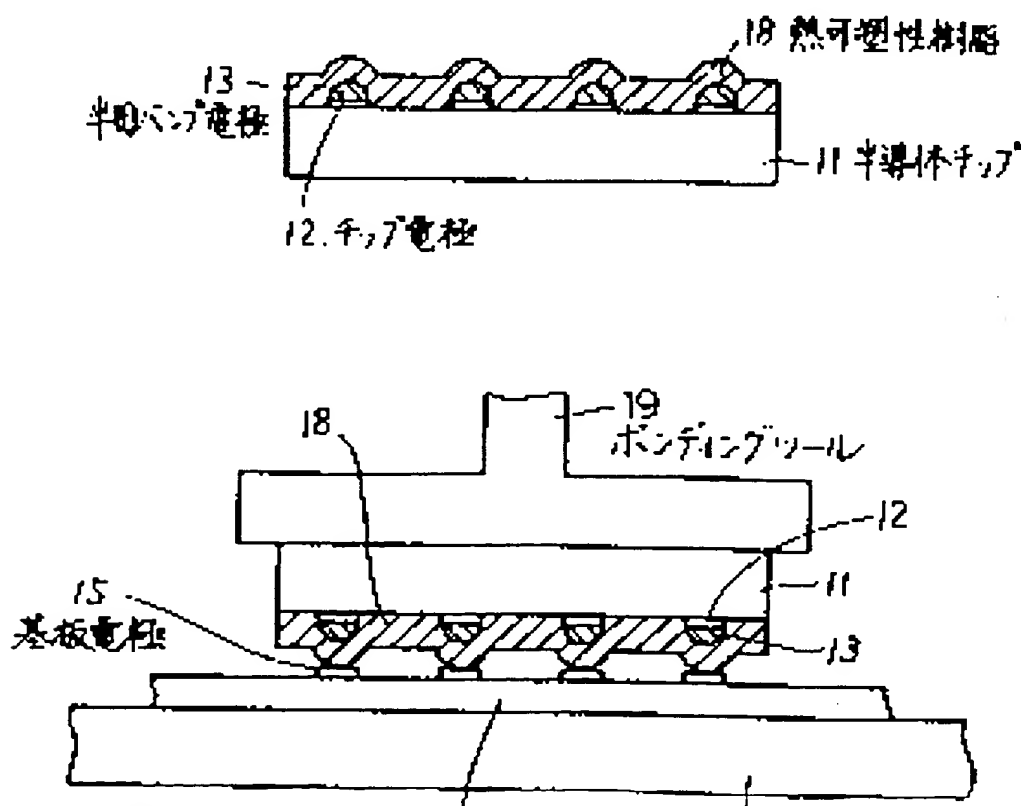
JAPIO Class: 42.2 (ELECTRONICS -- Solid State Components)

Journal: Section: E, Section No. 1050, Vol. 15, No. 125, Pg. 137, March 27, 1991 (19910327)

ABSTRACT

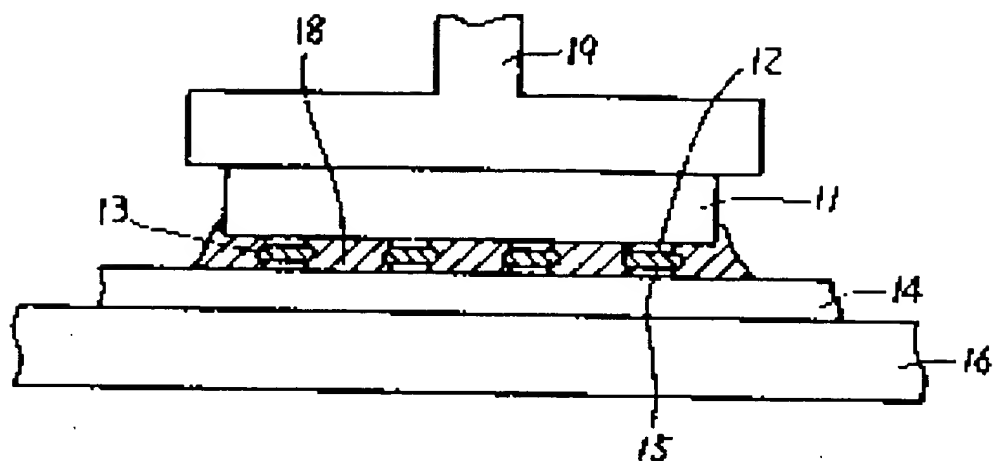
PURPOSE: To enable resin sealing of a clearance without generating bubbles by applying thermoplastic resin in advance and by heating the thermoplastic resin while pressurizing a semiconductor chip and a connection object in a direction to bring each electrode thereof into contact with each other.

CONSTITUTION: Thermoplastic resin 18 is applied in advance at least to either of a surface of a semiconductor chip 11 and a surface of a connection object. When the thermoplastic resin 18 is heated while pressurizing the semiconductor chip 11 and the connection object in a direction to bring each electrode thereof into contact with each other, the thermoplastic resin 18 extends inside a clearance formed by a surface of the semiconductor chip 11 and a surface of the connection object. Thereby, it is possible to seal the clearance which is formed by the surface of the semiconductor chip 11 and the surface of the connection object by the thermoplastic resin 18 without generating bubbles in the clearance.



14 回路基板

16 ホットプレート



JAPIO (Dialog® File 347): (c) 2001 JPO & JAPIO. All rights reserved.

©1997-2001 The Dialog Corporation -